

**APPLICATION NO. 09/786,597**

**CLEAN COPY OF THE SPECIFICATION**

On the both sides of the internal layer flexible circuit board, single-sided copper-clad laminates having the conduction layers 6 and 9 consisting of copper foils and the like are superimposed on the flexible insulating base materials 7 and 10 consisting of polyimide films through adhesive layers 8 and 11 of the pre-preg to constitute respective external layer circuit boards each of which can be a mounting portion.

Thereafter, upon forming a through hole 13 by NC drill means and the like, a through hole plated conduction portion 12 is formed by both using electroless plating means and electrolytic plating means, and a required wiring pattern is formed to the conduction layer of each external layer circuit board, thereby constituting a hybrid flexible multilayer circuit board 14 having a component mounting portion.